ISL28190, ISL28290

Single and Dual Single Supply Ultra-Low Noise, Ultra-Low Distortion, Rail-to-Rail Output, Op Amp

FN6247
Rev 11.00
September 8, 2015

The ISL28190 and ISL28290 are tiny single and dual ultra-low noise, ultra-low distortion operational amplifiers. Fully specified to operated down to +3V single supply. These amplifiers have outputs that swing rail-to-rail, and an input common mode voltage that extends below ground (ground sensing).

The ISL28190 and ISL28290 are unity gain stable with an input referred voltage noise of 1nV/√Hz. Both parts feature 0.00017% THD+N @ 1kHz.

The ISL28190 is available in the space-saving 6 Ld UTDFN (1.6mmx1.6mm) and 6 Ld SOT-23 packages. The ISL28290 is available in the 10 Ld UTQFN (1.8mmx1.4mm), 10 Ld MSOP and 8 LD SOIC packages. All devices are guaranteed over -40°C to +125°C.

Features

- 1nV/√Hz input voltage noise
- 1kHz THD+N typical 0.00017% at $2V_{P-P}$ V_{OUT}
- Harmonic Distortion -87dBc, -90dBc, f_o = 1MHz
- 170MHz -3dB bandwidth
- 50V/µs slew rate
- 700µV maximum offset voltage
- 10µA typical input bias current
- 103dB typical CMRR
- 3V to 5.5V single supply voltage range
- Rail-to-rail output
- Ground sensing
- Enable pin (not available in the 8 Ld SOIC package option)
- Pb-free (RoHS compliant)

Applications

- Low noise signal processing
- Low noise microphones/preamplifiers
- ADC buffers
- DAC output amplifiers
- Digital scales
- Strain gauges/sensor amplifiers
- Radio systems
- Portable equipment
- Infrared detectors

Ordering Information

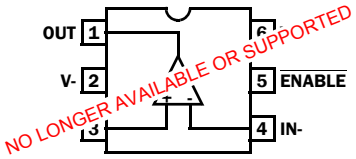
PART NUMBER (Note 5)	PART MARKING	PACKAGE (RoHS Compliant)	PKG. DWG. #
ISL28190FHZ-T7 (Notes 1, 2) **(No longer available or supported)**	GABH (Note 4)	6 Ld SOT-23	P6.064A
ISL28190FRUZ-T7 (Notes 1, 3) **(No longer available or supported)**	M7	6 Ld UTDFN	L6.1.6x1.6A
ISL28290FUZ (Note 2)	8290Z	10 Ld MSOP	M10.118A
ISL28290FUZ-T7 (Note 1)	8290Z	10 Ld MSOP	M10.118A
ISL28290FRUZ-T7 (Notes 1, 3)	E	10 Ld UTQFN	L10.1.8x1.4A
ISL28290FBZ (Note 2)	28290 FBZ	8 Ld SOIC	M8.15E
ISL28290FBZ-T7 (Note 1)	28290 FBZ	8 Ld SOIC	M8.15E
ISL28190EVAL1Z **(No longer available or supported)**	Evaluation Board		
ISL28290EVAL1Z	Evaluation Board		

NOTES:

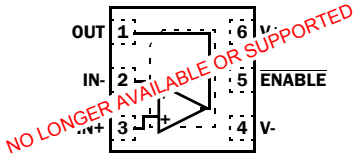
1. Please refer to TB347 for details on reel specifications.
2. These Intersil Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
3. These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and NiPdAu plate - e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
4. The part marking is located on the bottom of the part.
5. For Moisture Sensitivity Level (MSL), please see device information page for ISL28190, ISL28290. For more information on MSL please see tech brief TB363.

Pin Configurations

ISL28190
(6 LD SOT-23)
TOP VIEW

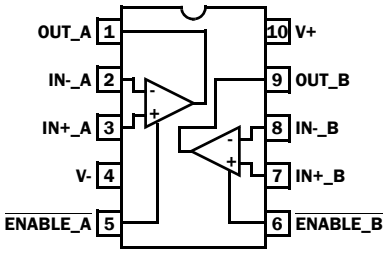


ISL28190
(6 LD 1.6x1.6x0.5 UTDFN)
TOP VIEW

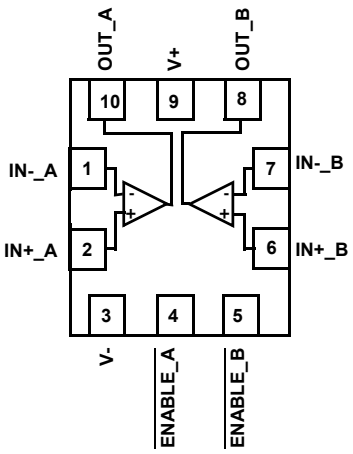


Pin Configurations

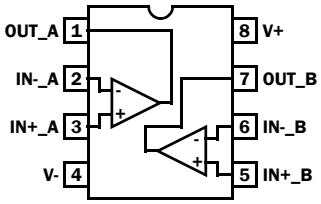
ISL28290
(10 LD MSOP)
TOP VIEW



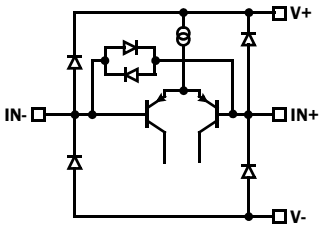
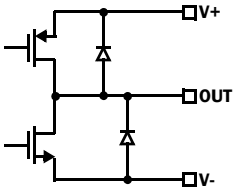
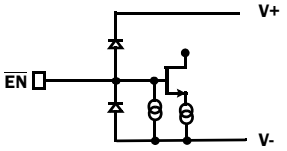
ISL28290
(10 LD UTQFN)
TOP VIEW



ISL28290
(8 LD SOIC)
TOP VIEW



Pin Descriptions

ISL28190 (6 Ld SOT-23)	ISL28190 (6 Ld UTDFN)	ISL28290 (10 Ld MSOP)	ISL28290 (10 Ld UTQFN)	ISL28290 (8 Ld SOIC)	PIN NAME	FUNCTION	EQUIVALENT CIRCUIT
4	2	2 (A) 8 (B)	1 (A) 7 (B)	2 (A) 6 (B)	IN- IN-_A IN-_B	Inverting input	 Circuit 1
3	3	3 (A) 7 (B)	2 (A) 6 (B)	3 (A) 5 (B)	IN+ IN+_A IN+_B	Non-inverting input	(See Circuit 1)
2	4	4	3	4	V-	Negative supply	
1	1	1 (A) 9 (B)	10 (A) 8 (B)	1 (A) 7 (B)	OUT OUT_A OUT_B	Output	 Circuit 2
6	6	10	9	8	V+	Positive supply	
5	5	5 (A) 6 (B)	4 (A) 5 (B)	N/A	$\overline{EN}$ $\overline{EN}$_A $\overline{EN}$_B	Enable BAR pin internal pull-down; Logic “1” selects the disabled state; Logic “0” selects the enabled state.	 Circuit 3

Absolute Maximum Ratings (T_A = +25°C)

Supply Voltage 5.5V
Supply Turn On Voltage Slew Rate 1V/µs
Differential Input Current 5mA
Differential Input Voltage 0.5V
Input Voltage . . . . . V- - 0.5V to V+ + 0.5V
ESD Tolerance
Human Body Model 3kV
Machine Model 300V
Charged Device Model 1200V

Thermal Information

Thermal Resistance (Typical)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
6 Ld SOT-23 Package (Notes 6, 9)	170	105
6 Ld UTDFN Package (Notes 7, 8)	125	80
8 Ld SOIC Package (Notes 6, 9)	110	82
10 Ld MSOP Package (Notes 6, 9)	175	90
10 Ld UTQFN Package (Notes 6, 9)	190	140

Ambient Operating Temperature Range . . . . . -40°C to +125°C
Storage Temperature Range . . . . . -65°C to +150°C
Operating Junction Temperature . . . . . +125°C
Pb-Free Reflow Profile . . . . . see link below
http://www.intersil.com/pbfree/Pb-FreeReflow.asp

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTE:

6. θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air. See Tech Brief TB379 for details.
7. θ_{JA} is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379.
8. For θ_{JC}, the "case temp" location is the center of the exposed metal pad on the package underside.
9. For θ_{JC}, the "case temp" location is taken at the package top center.

Electrical Specifications

V+ = 5.0V, V- = GND, R_L = Open, R_F = 1kΩ, A_V = -1 unless otherwise specified. Parameters are per amplifier. Typical values are at V+ = 5V, T_A = +25°C. **Boldface limits apply over the operating temperature range, -40°C to +125°C, temperature data established by characterization.**

PARAMETER	DESCRIPTION	CONDITIONS	MIN (Note 10)	TYP	MAX (Note 10)	UNIT
DC SPECIFICATIONS						
V_{OS}	Input Offset Voltage		-1100	240	700	µV
					900	
$\frac{\Delta V_{OS}}{\Delta T}$	Input Offset Drift vs Temperature	See Figure 21		1.9		µV/°C
I_{IO}	Input Offset Current			40	500	nA
					900	
I_B	Input Bias Current			10	16	µA
					18	
V_{CM}	Common-Mode Voltage Range		**0**		**3.8**	V
CMRR	Common-Mode Rejection Ratio	V_{CM} = 0V to 3.8V	78	103		dB
PSRR	Power Supply Rejection Ratio	V_S = 3V to 5V	74	80		dB
A_{VOL}	Large Signal Voltage Gain	V_O = 0.5V to 4V, R_L = 1kΩ	94	102		dB
			90			
V_{OUT}	Maximum Output Voltage Swing	Output low, R_L = 1kΩ		20	50	mV
					80	
		Output high, R_L = 1kΩ, V+ = 5V	4.95	4.97		V
			4.92			
$I_{S,ON}$	Supply Current per Channel, Enabled			8.5	11	mA
					13	
$I_{S,OFF}$	Supply Current, Disabled			26	35	µA
					52	
I_O+	Short-Circuit Output Current	R_L = 10Ω	95	144		mA
			90			

Electrical Specifications V+ = 5.0V, V- = GND, R_L = Open, R_F = 1kΩ, A_V = -1 unless otherwise specified. Parameters are per amplifier. Typical values are at V+ = 5V, T_A = +25°C. **Boldface limits apply over the operating temperature range, -40°C to +125°C, temperature data established by characterization. (Continued)**

PARAMETER	DESCRIPTION	CONDITIONS	MIN (Note 10)	TYP	MAX (Note 10)	UNIT
I_{O-}	Short-Circuit Output Current	R_L = 10Ω	95	135		mA
			90			
V_{SUPPLY}	Supply Operating Range	V+ to V-	**3**		**5.5**	V
$V_{\overline{ENH}}$	$\overline{EN}$ High Level	Referred to V-	**2**			V
$V_{\overline{ENL}}$	$\overline{EN}$ Low Level	Referred to V-			**0.8**	V
$I_{\overline{ENH}}$	$\overline{EN}$ Pin Input High Current	$V_{\overline{EN}}$ = V+		0.8	1.2	µA
					1.4	
$I_{\overline{ENL}}$	$\overline{EN}$ Pin Input Low Current	$V_{\overline{EN}}$ = V-		20	80	nA
					100	
AC SPECIFICATIONS						
GBW	-3dB Unity Gain Bandwidth	R_F = 0Ω C_L = 20pF, A_V = 1, R_L = 10kΩ		170		MHz
THD+N	Total Harmonic Distortion + Noise	f = 1kHz, VOUT + $2V_{P-P}$, A_V = +1, R_L = 10kΩ		0.00017		%
HD (1MHz)	2nd Harmonic Distortion	V_{OUT} = $2V_{P-P}$, A_V = 1		-87		dBc
	3rd Harmonic Distortion			-90		dBc
ISO	Off-state Isolation f_O = 100kHz	A_V = +1; V_{IN} = $100mV_{P-P}$; R_F = 0Ω, C_L = 20pF, A_V = 1, R_L = 10kΩ		-38		dB
X-TALK ISL28290	Channel-to-Channel Crosstalk f_O = 100kHz	V_S = ±2.5V; A_V = +1; V_{IN} = $1V_{P-P}$, R_F = 0Ω, C_L = 20pF, A_V = 1, R_L = 10kΩ		-105		dB
PSRR	Power Supply Rejection Ratio f_O = 100kHz	V_S = ±2.5V; A_V = +1; V_{SOURCE} = $1V_{P-P}$, R_F = 0Ω, C_L = 20pF, A_V = 1, R_L = 10kΩ		-70		dB
CMRR	Common Mode Rejection Ratio f_O = 100kHz	V_S = ±2.5V; A_V = +1; V_{CM} = $1V_{P-P}$, R_F = 0Ω, C_L = 20pF, A_V = 1, R_L = 10kΩ		-65		dB
e_n	Input Referred Voltage Noise	f_O = 1kHz		1		nV/√Hz
i_n	Input Referred Current Noise	f_O = 10kHz		2.1		pA/√Hz
TRANSIENT RESPONSE						
SR	Slew Rate		30	50		V/µs
			25			
t_{pd}	Propagation Delay 10% V_{IN} - 10% V_{OUT}	A_V = 1, V_{OUT} = $100mV_{P-P}$, R_F = 0Ω, C_L = 1.2pF		1.0		ns
t_r, t_f, Small Signal	Rise Time, t_r 10% to 90%	A_V = +1, V_{OUT} = $0.1V_{P-P}$, R_F = 0Ω, C_L = 1.2pF		3.3		ns
	Fall Time, t_f 10% to 90%			6.3		ns
t_r, t_f Large Signal	Rise Time, t_r 10% to 90%	A_V = +2, V_{OUT} = $1V_{P-P}$, R_F = R_G = 499Ω, R_L = 10kΩ, C_L = 1.2pF		44		ns
	Fall Time, t_f 10% to 90%			51		ns
	Rise Time, t_r 10% to 90%	A_V = +2, V_{OUT} = $4.7V_{P-P}$, R_F = R_G = 499Ω, R_L = 10kΩ, C_L = 1.2pF		190		ns
	Fall Time, t_f 10% to 90%			187		ns
t_s	Settling Time to 0.1% 90% V_{OUT} to 0.1% V_{OUT}	A_V = 1, V_{OUT} = $1V_{P-P}$, R_F = 0Ω, C_L = 1.2pF		45		ns
$t_{\overline{EN}}$	ENABLE to Output Turn-on Delay Time; 10% $\overline{EN}$ - 10% V_{OUT}	A_V = 1, V_{OUT} = 1VDC, R_L = 10kΩ, C_L = 1.2pF		330		ns
	ENABLE to Output Turn-off Delay Time; 10% $\overline{EN}$ - 10% V_{OUT}	A_V = 1, V_{OUT} = 0VDC, R_L = 10kΩ, C_L = 1.2pF		50		ns

NOTE:

10. Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design.

Typical Performance Curves

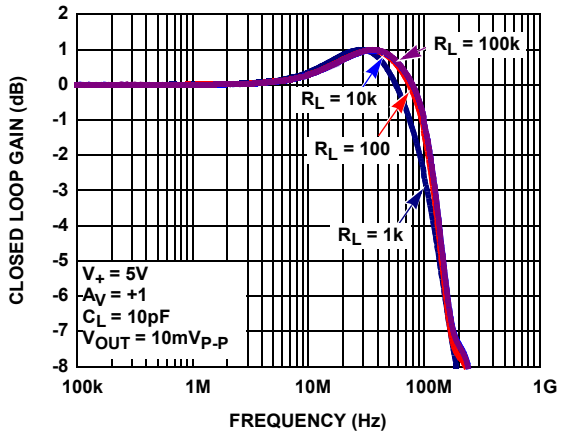


FIGURE 1. GAIN vs FREQUENCY FOR VARIOUS R_{LOAD}

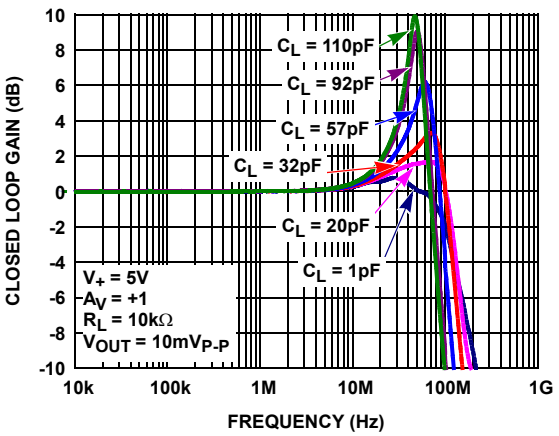


FIGURE 2. GAIN vs FREQUENCY FOR VARIOUS C_{LOAD}

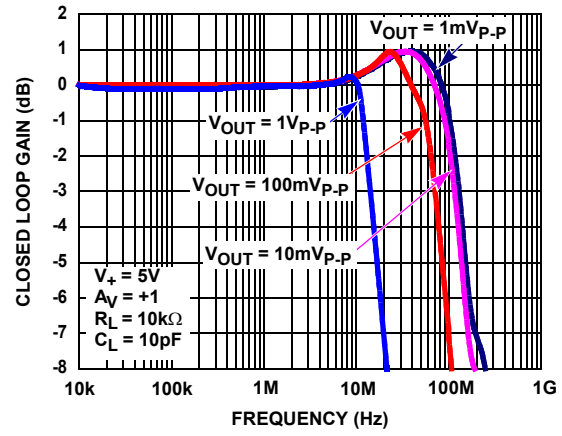


FIGURE 3. -3dB BANDWIDTH vs V_{OUT}

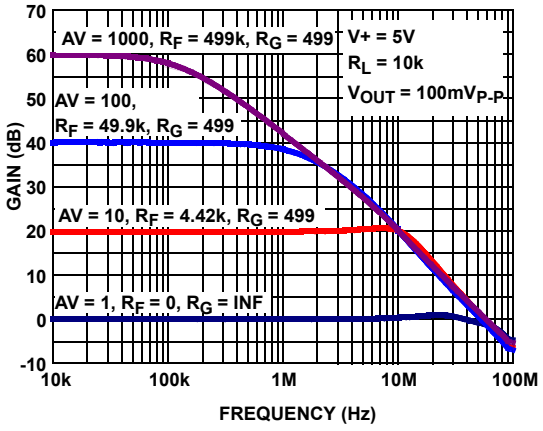


FIGURE 4. FREQUENCY RESPONSE vs CLOSED LOOP GAIN

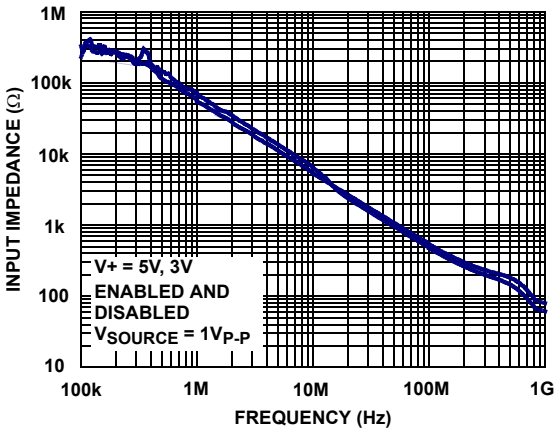


FIGURE 5. INPUT IMPEDANCE vs FREQUENCY

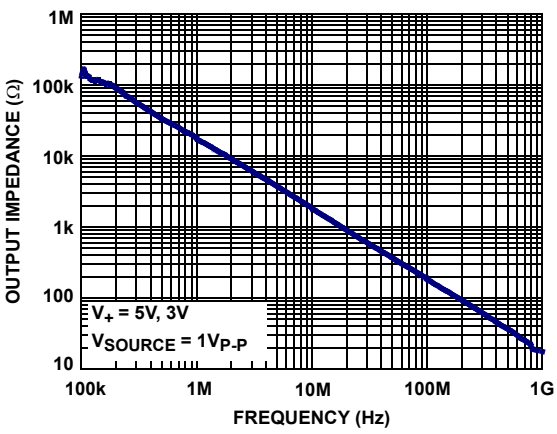


FIGURE 6. DISABLED OUTPUT IMPEDANCE vs FREQUENCY

Typical Performance Curves (Continued)

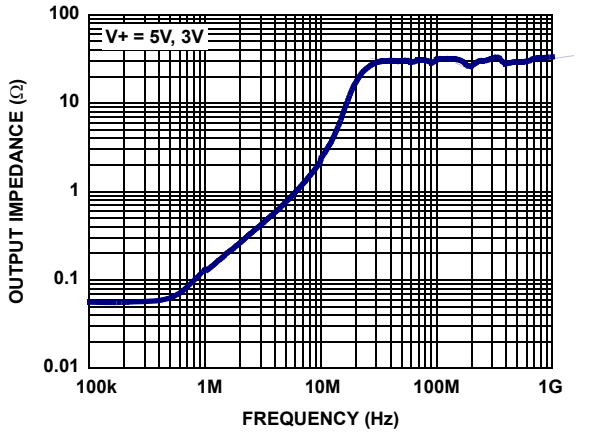


FIGURE 7. ENABLED OUTPUT IMPEDANCE vs FREQUENCY

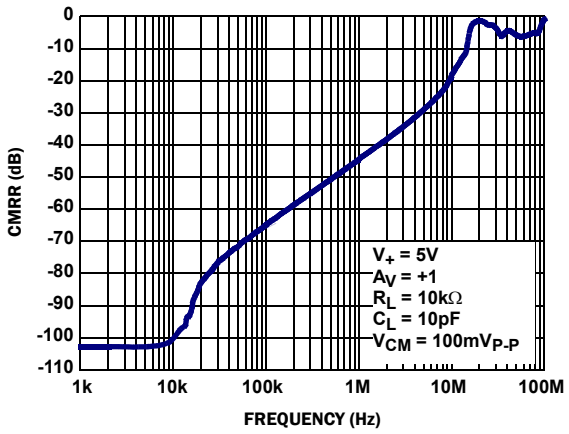


FIGURE 8. CMRR vs FREQUENCY

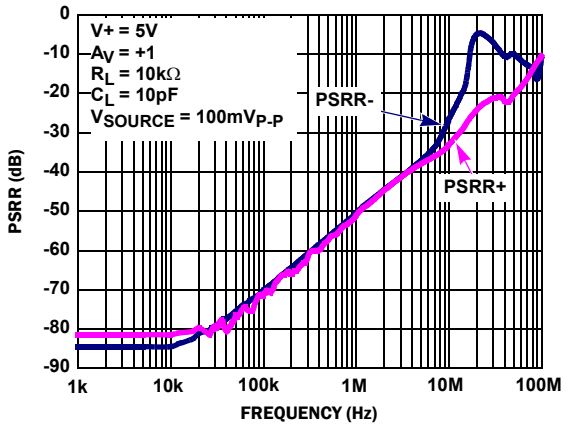


FIGURE 9. PSRR vs FREQUENCY

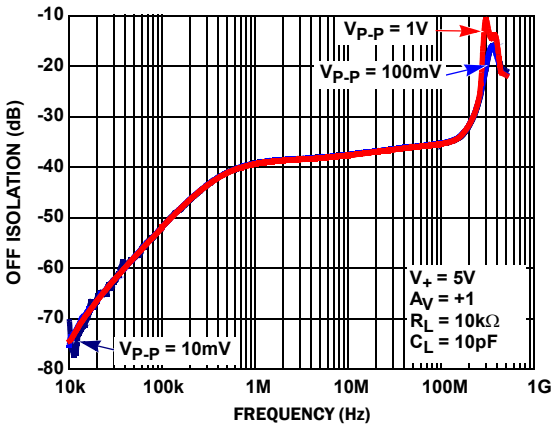


FIGURE 10. OFF ISOLATION vs FREQUENCY

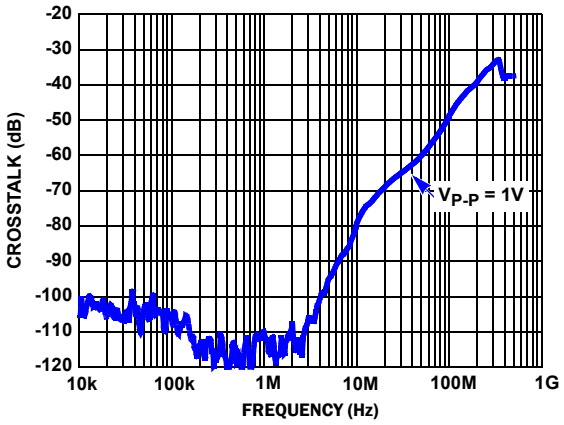


FIGURE 11. CHANNEL-TO-CHANNEL CROSSTALK vs FREQUENCY

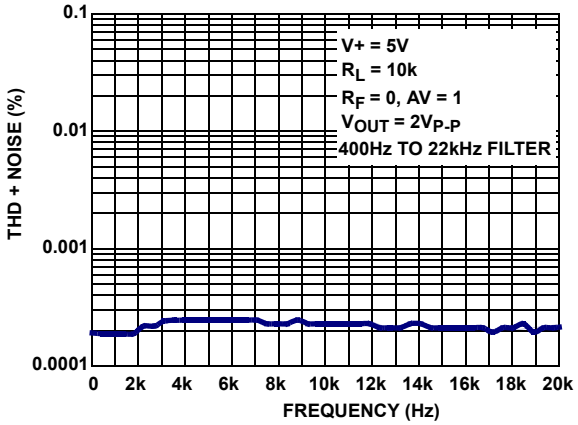


FIGURE 12. THD+N vs FREQUENCY

Typical Performance Curves (Continued)

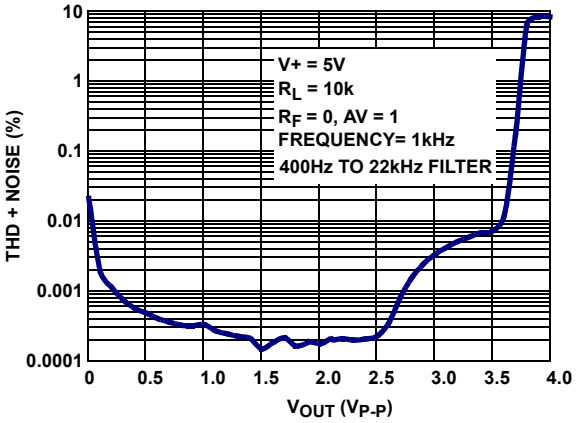


FIGURE 13. THD+N @ 1kHz vs V_{OUT}

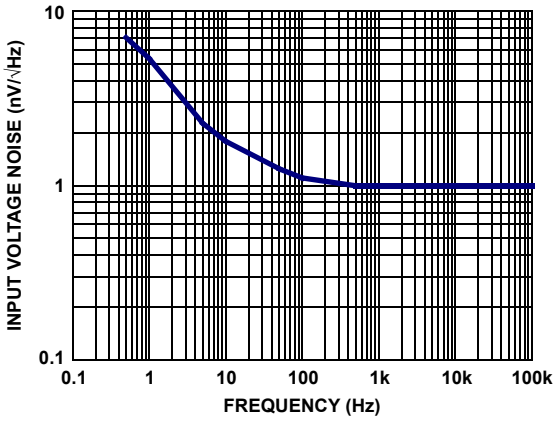


FIGURE 14. INPUT REFERRED NOISE VOLTAGE vs FREQUENCY

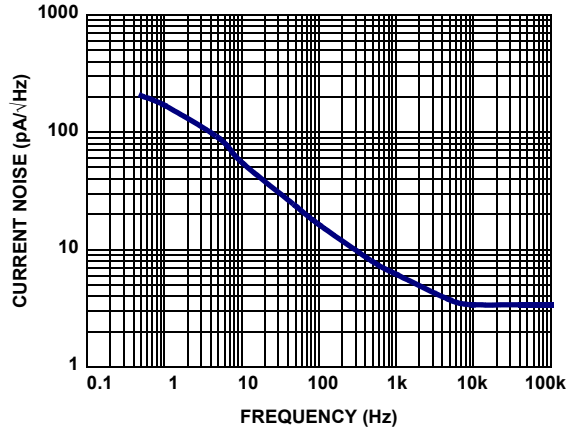


FIGURE 15. INPUT REFERRED NOISE CURRENT vs FREQUENCY

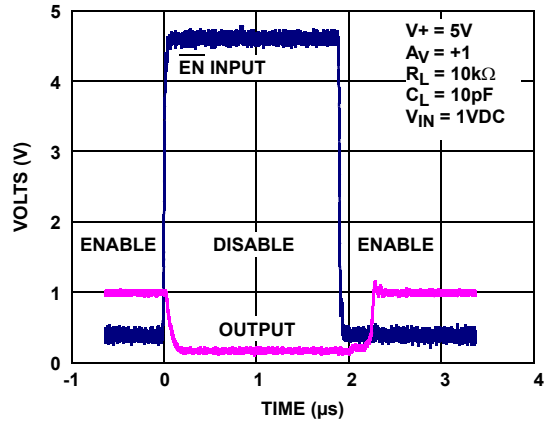


FIGURE 16. ENABLE/DISABLE TIMING

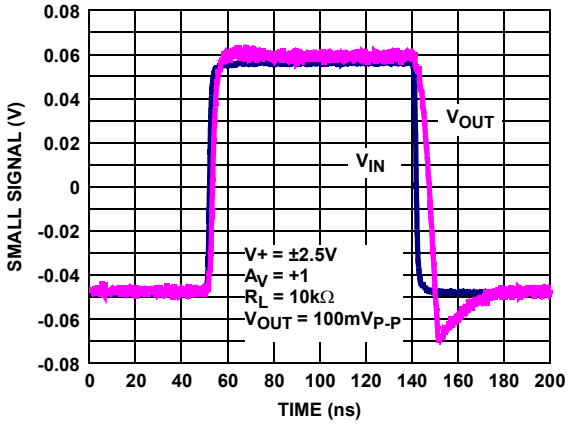


FIGURE 17. SMALL SIGNAL STEP RESPONSE

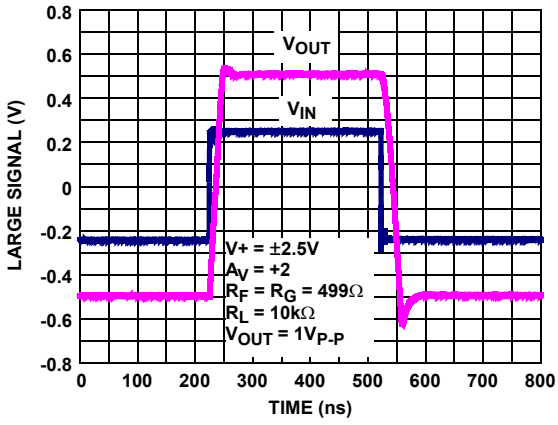


FIGURE 18. LARGE SIGNAL (1V) STEP RESPONSE

Typical Performance Curves (Continued)

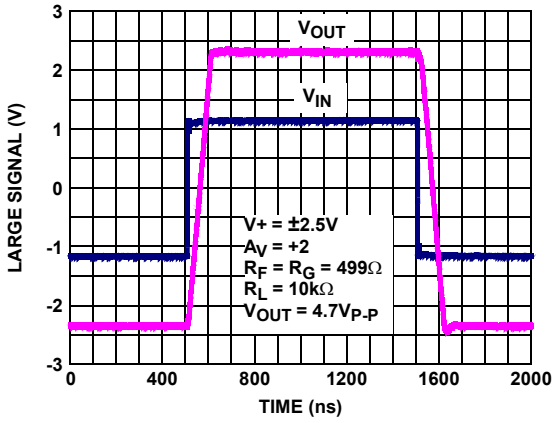


FIGURE 19. LARGE SIGNAL (4.7V) STEP RESPONSE

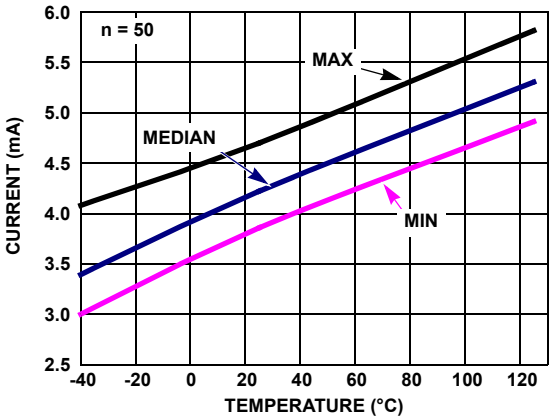


FIGURE 20. SUPPLY CURRENT vs TEMPERATURE, V_S = ±2.5V ENABLED, R_L = INF

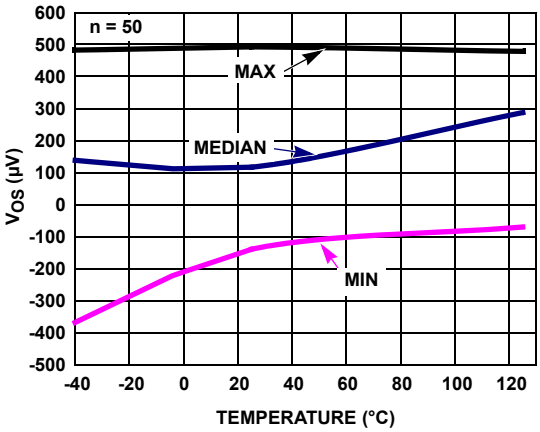


FIGURE 21. V_{OS} vs TEMPERATURE V_S = ±2.5V

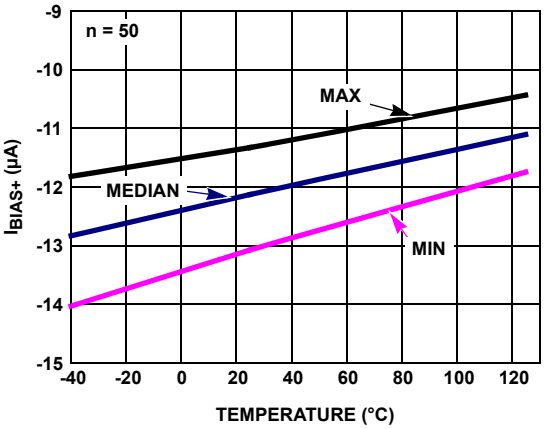


FIGURE 22. I_{BIAS+} vs TEMPERATURE V_S = ±2.5V

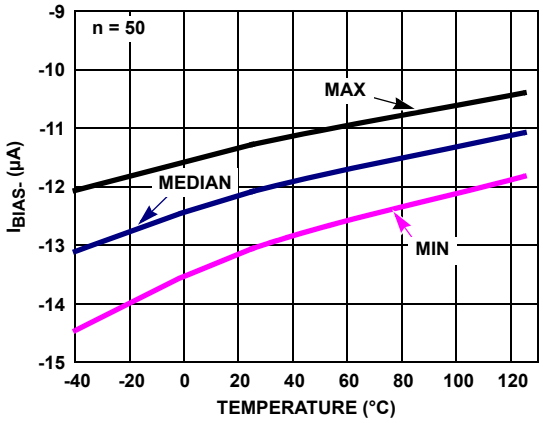


FIGURE 23. I_{BIAS-} vs TEMPERATURE V_S = ±2.5V

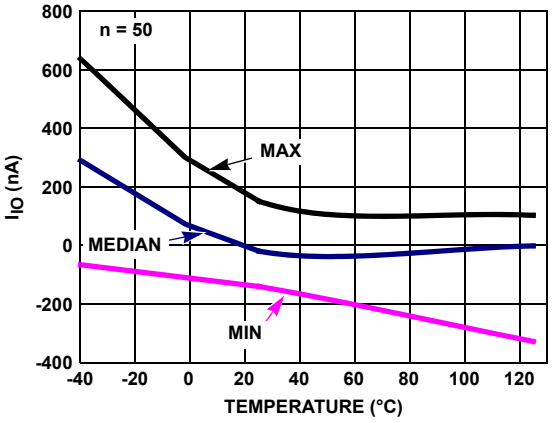


FIGURE 24. I_{IO} vs TEMPERATURE V_S = ±2.5V

Typical Performance Curves (Continued)

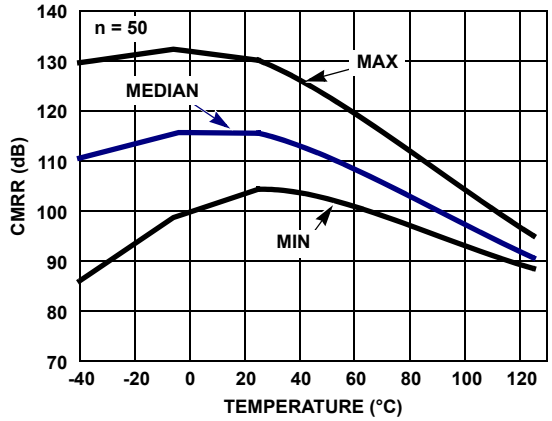


FIGURE 25. CMRR vs TEMPERATURE, VCM = 3.8V, V_S = ±2.5V

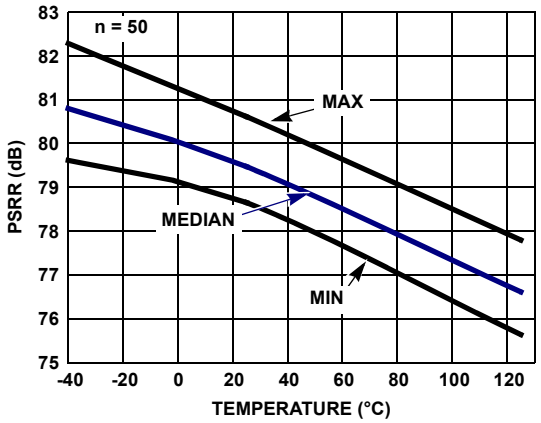


FIGURE 26. PSRR vs TEMPERATURE ±1.5V TO ±2.5V

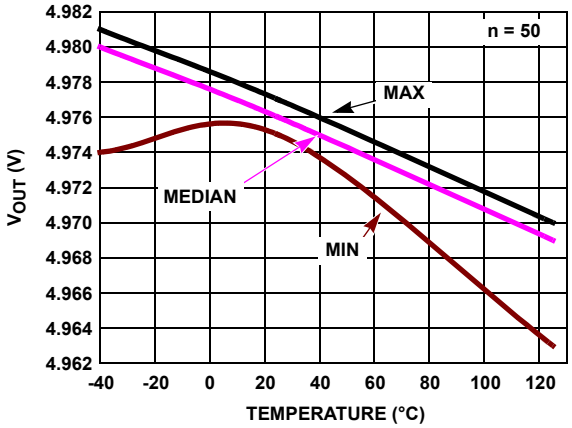


FIGURE 27. POSITIVE V_{OUT} vs TEMPERATURE R_L = 1k, V_S = ±2.5V

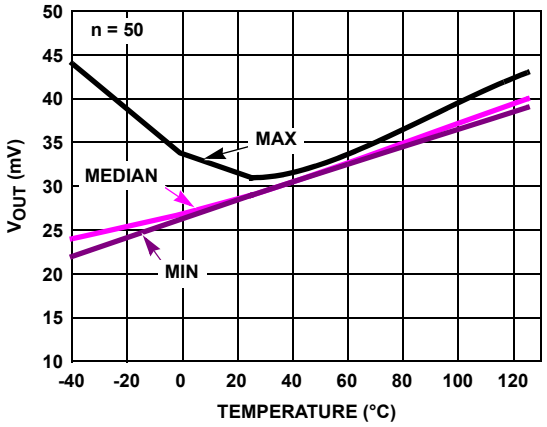


FIGURE 28. NEGATIVE V_{OUT} vs TEMPERATURE R_L = 1k, V_S = ±2.5V

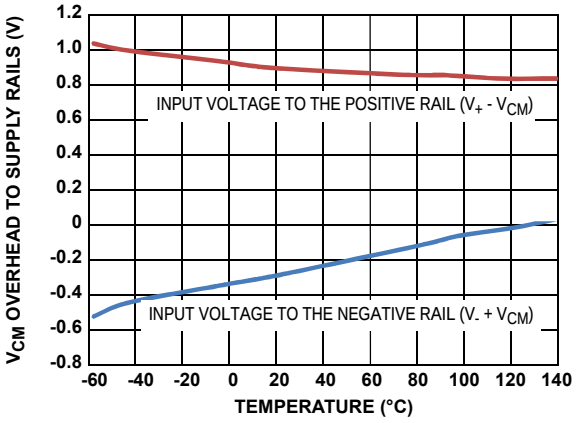


FIGURE 29. INPUT COMMON MODE VOLTAGE vs TEMPERATURE

Applications Information

Product Description

The ISL28190 and ISL28290 are voltage feedback operational amplifiers designed for communication and imaging applications requiring low distortion, very low voltage and current noise. Both parts feature high bandwidth while drawing moderately low supply current. The ISL28190 and ISL28290 use a classical voltage-feedback topology, which allows them to be used in a variety of applications where current-feedback amplifiers are not appropriate because of restrictions placed upon the feedback element used with the amplifier.

Enable/Power-Down

The ISL28190 and ISL28290 amplifiers are disabled by applying a voltage greater than 2V to the $\overline{EN}$ pin, with respect to the V- pin. In this condition, the output(s) will be in a high impedance state and the amplifier(s) current will be reduced to 13µA/Amp. By disabling the part, multiple parts can be connected together as a MUX. The outputs are tied together in parallel and a channel can be selected by the $\overline{EN}$ pin. The $\overline{EN}$ pin also has an internal pull-down. If left open, the $\overline{EN}$ pin will pull to the negative rail and the device will be enabled by default.

Input Protection

All input terminals have internal ESD protection diodes to both positive and negative supply rails, limiting the input voltage to within one diode beyond the supply rails. Both parts have additional back-to-back diodes across the input terminals (as shown in Figure 30). In pulse applications where the input Slew Rate exceeds the Slew Rate of the amplifier, the possibility exists for the input protection diodes to become forward biased. This can cause excessive input current and distortion at the outputs. If overdriving the inputs is necessary, the external input current must never exceed 5mA. An external series resistor may be used to limit the current, as shown in Figure 30.

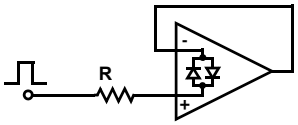


FIGURE 30. LIMITING THE INPUT CURRENT TO LESS THAN 5mA

Using Only One Channel

The ISL28290 is a Dual channel op amp. If the application only requires one channel when using the ISL28290, the user must configure the unused channel to prevent it from oscillating. Oscillation can occur if the input and output pins are floating. This will result in higher than expected supply currents and possible noise injection into the channel being used. The proper way to prevent this oscillation is to short the output to the negative input and ground the positive input (as shown in Figure 31).

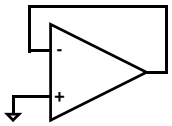


FIGURE 31. PREVENTING OSCILLATIONS IN UNUSED CHANNELS

Power Supply Bypassing and Printed Circuit Board Layout

As with any high frequency device, good printed circuit board layout is necessary for optimum performance. Low impedance ground plane construction is essential. Surface mount components are recommended, but if leaded components are used, lead lengths should be as short as possible. The power supply pins must be well bypassed to reduce the risk of oscillation. The combination of a 4.7µF tantalum capacitor in parallel with a 0.01µF capacitor has been shown to work well when placed at each supply pin.

For good AC performance, parasitic capacitance should be kept to a minimum, especially at the inverting input. When ground plane construction is used, it should be removed from the area near the inverting input to minimize any stray capacitance at that node. Carbon or Metal-Film resistors are acceptable with the Metal-Film resistors giving slightly less peaking and bandwidth because of additional series inductance. Use of sockets, particularly for the SO package, should be avoided if possible. Sockets add parasitic inductance and capacitance, which will result in additional peaking and overshoot.

Current Limiting

The ISL28190 and ISL28290 have no internal current-limiting circuitry. If the output is shorted, it is possible to exceed the Absolute Maximum Rating for output current or power dissipation, potentially resulting in the destruction of the device. This is why output short circuit current is specified and tested with $R_L = 10\Omega$.

Power Dissipation

It is possible to exceed the +125°C maximum junction temperatures under certain load and power-supply conditions. It is therefore important to calculate the maximum junction temperature (T_{JMAX}) for all applications to determine if power supply voltages, load conditions, or package type need to be modified to remain in the safe operating area. These parameters are related as follows:

$$T_{JMAX} = T_{MAX} + (\theta_{JA} x PD_{MAXTOTAL}) \quad \text{(EQ. 1)}$$

where:

- $P_{DMAXTOTAL}$ is the sum of the maximum power dissipation of each amplifier in the package (PD_{MAX})
- PD_{MAX} for each amplifier can be calculated as follows:

$$PD_{MAX} = 2*V_S \times I_{SMAX} + (V_S - V_{OUTMAX}) \times \frac{V_{OUTMAX}}{R_L} \quad \text{(EQ. 2)}$$

where T_{MAX} = Maximum ambient temperature

- θ_{JA} = Thermal resistance of the package
- PD_{MAX} = Maximum power dissipation of 1 amplifier
- V_S = Supply voltage
- I_{MAX} = Maximum supply current of 1 amplifier
- V_{OUTMAX} = Maximum output voltage swing of the application
- R_L = Load resistance

Revision History

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

DATE	REVISION	CHANGE
September 8, 2015	FN6247.11	Updated Ordering Information Table on page 2. stamped ISL28190 pin configurations
July 22, 2014	FN6247.10	page 5 - Updated Thermal Information table. Updated location of note references. Updated POD L10.1.8x1.4A : Bottom view- added chamfer dimension C0.10. Land pattern - removed the chamfer lead footprint, added footprint tip to tip dimension (2.20 & 1.80). Added SOIC package for ISL28290 to description on page 1.
January 18, 2012	FN6247.9	“Ordering Information” on page 2: Added Eval Board ISL28190EVAL1Z ISL28190FHZ-T7 - Pkg. Dwg. # changed from MDP0038 TO P6.064A ISL28290FUZ - Pkg. Dwg. # changed from MDP0043 to M10.118A ISL28290FBZ - Pkg. Dwg. # changed from MDP0027 to M8.15E Changed µTDFN and TQFN to ultra matching package outline drawing descriptions Added MSL Note 5 and SOT-23 Note 4 “Thermal Information” on page 5: 10 Ld UTQFN θ_{JA} changed from "180" to "143" 8 LD SOIC θ_{JA} changed from "125" to "110" “Electrical Specifications” table change on page 6: Updated note in Min Max column of spec tables from "Parameters with MIN and/or MAX limits are 100% tested at +25°C, unless otherwise specified. Temperature limits established by characterization and are not production tested." to "Compliance to datasheet limits is assured by one or more methods: production test, characterization and/or design." “Typical Performance Curves” change on page 11: Added Figure 29 “INPUT COMMON MODE VOLTAGE vs TEMPERATURE” Updated Package Outline Drawings: Page 15 - MDP0038 to P6.064A - chgd from multiple pkgs to individual no dimension changes Page 18 - MDP0027 to M8.15E - chgd from multiple pkgs to individual no dimension changes Page 19 - MDP0043 to M10.118A - chgd from multiple pkgs to individual no dimension changes

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Intersil Corporation is a leading provider of innovative power management and precision analog solutions. The company's products address some of the largest markets within the industrial and infrastructure, mobile computing and high-end consumer markets.

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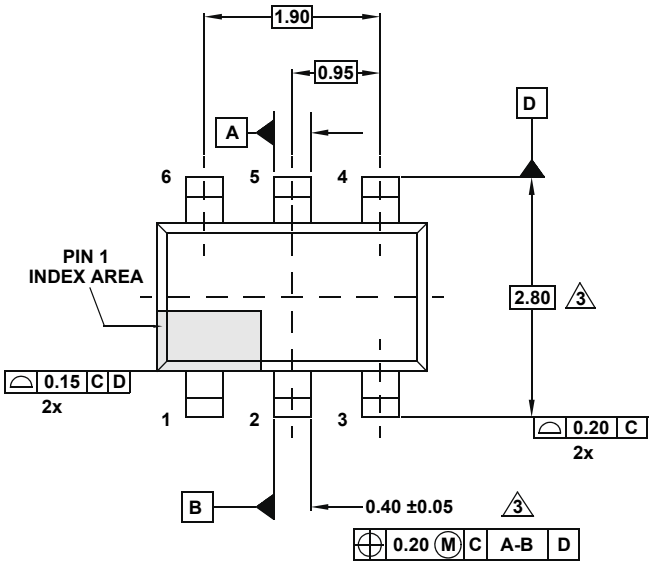
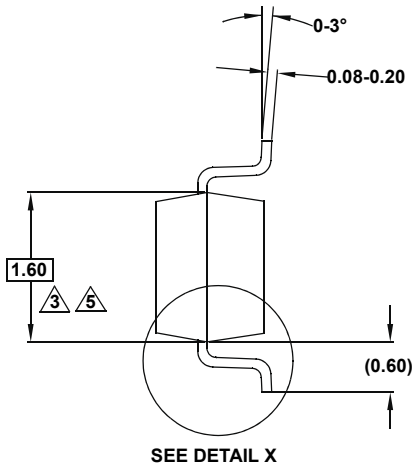
Package Outline Drawing

P6.064A

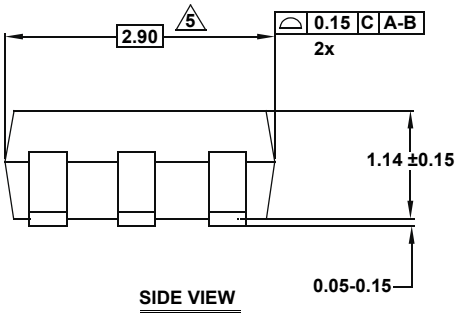
6 LEAD SMALL OUTLINE TRANSISTOR PLASTIC PACKAGE
Rev 0, 2/10



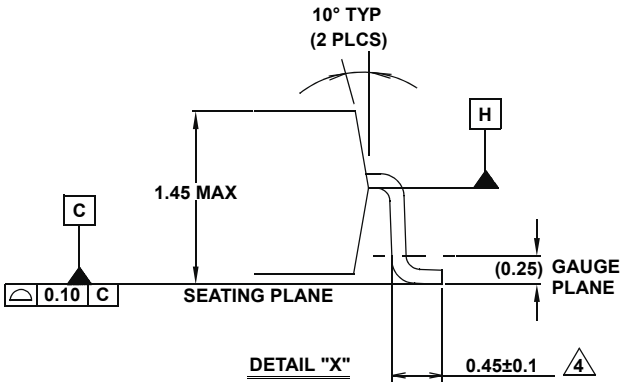
TOP VIEW



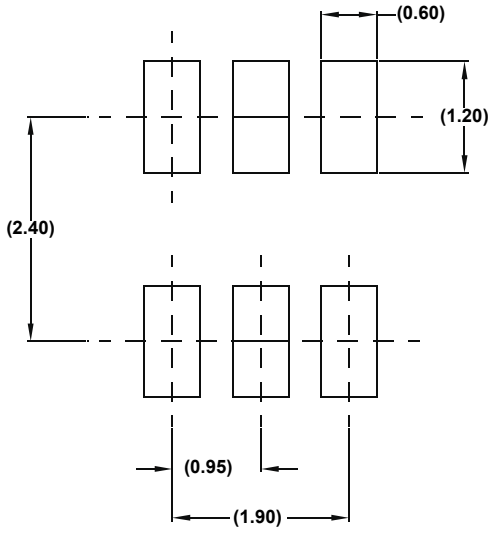
END VIEW



SIDE VIEW



DETAIL "X"

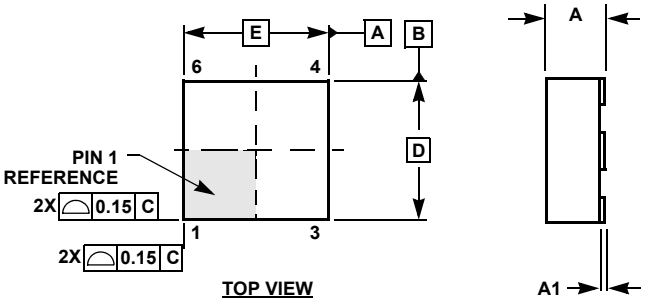


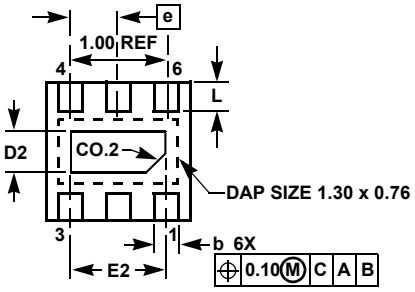
TYPICAL RECOMMENDED LAND PATTERN

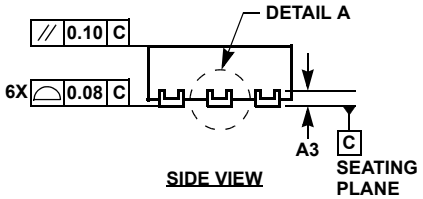
NOTES:

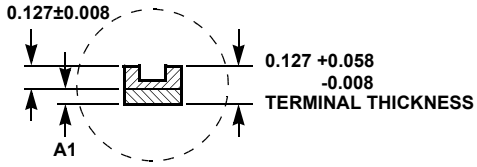
1. Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
3. Dimension is exclusive of mold flash, protrusions or gate burrs.
4. Foot length is measured at reference to guage plane.
5. This dimension is measured at Datum “H”.
6. Package conforms to JEDEC MO-178AA.

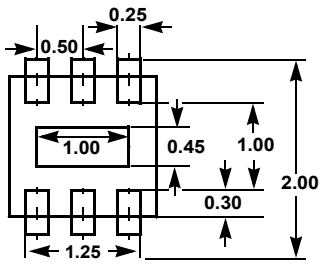
Ultra Thin Dual Flat No-Lead Plastic Package (UTDFN)











L6.1.6x1.6A

6 LEAD ULTRA THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3		0.127 REF		-
b	0.15	0.20	0.25	-
D	1.55	1.60	1.65	4
D2	0.40	0.45	0.50	-
E	1.55	1.60	1.65	4
E2	0.95	1.00	1.05	-
e		0.50 BSC		-
L	0.25	0.30	0.35	-

Rev. 1 6/06

NOTES:

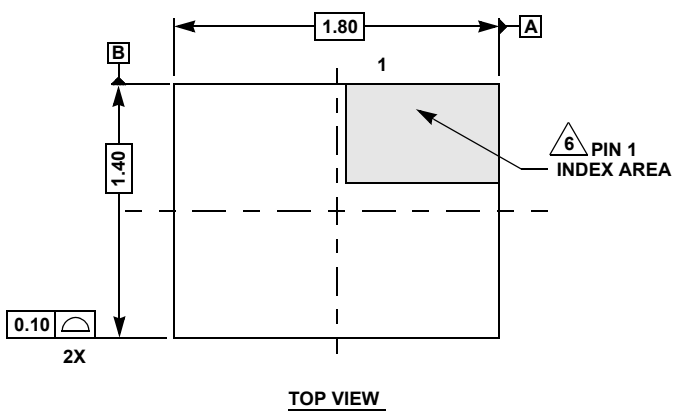
1. Dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed pad as well as the terminals. Coplanarity shall not exceed 0.08mm.
3. Warpage shall not exceed 0.10mm.
4. Package length/package width are considered as special characteristics.
5. JEDEC Reference MO-229.
6. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.

Package Outline Drawing

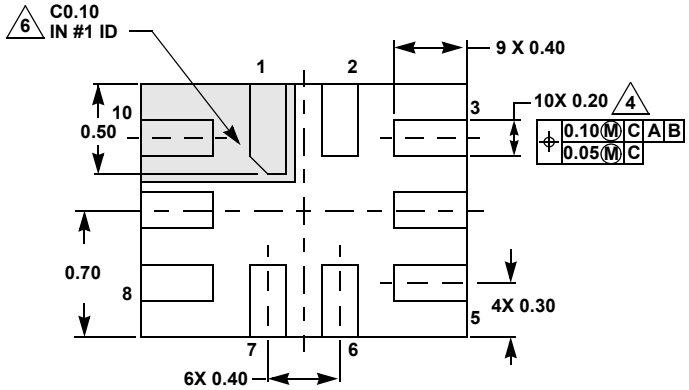
L10.1.8x1.4A

10 LEAD ULTRA THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

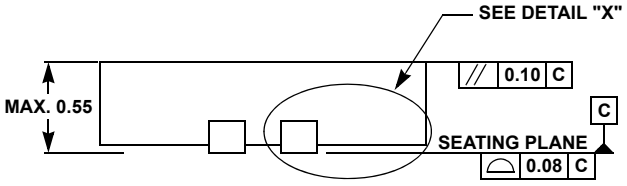
Rev 6, 8/13



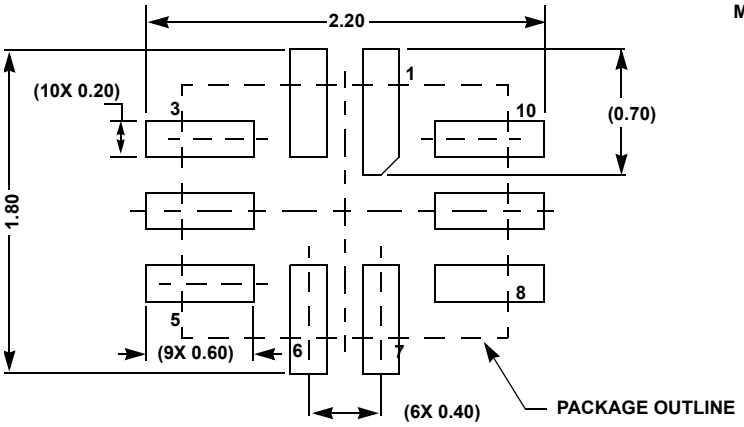
TOP VIEW



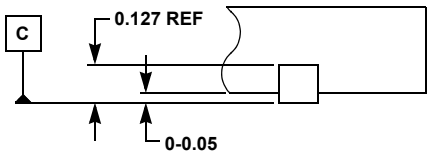
BOTTOM VIEW



SIDE VIEW



TYPICAL RECOMMENDED LAND PATTERN



DETAIL "X"

NOTES:

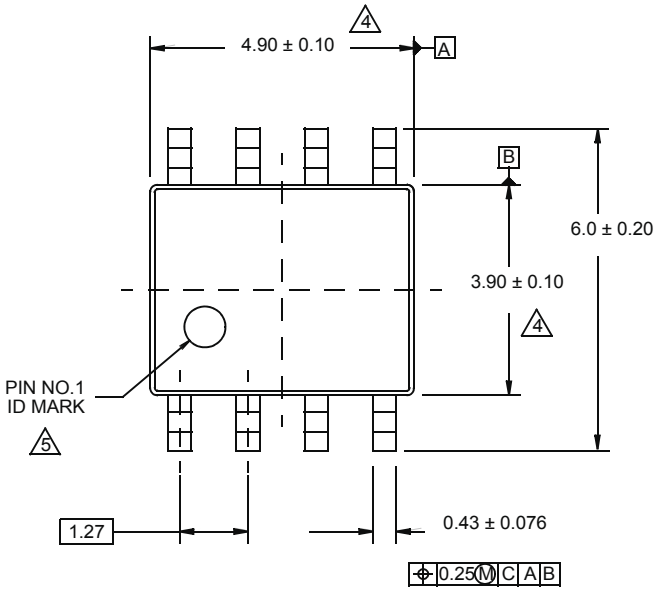
1. Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Lead width dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
5. JEDEC reference MO-255.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.

Package Outline Drawing

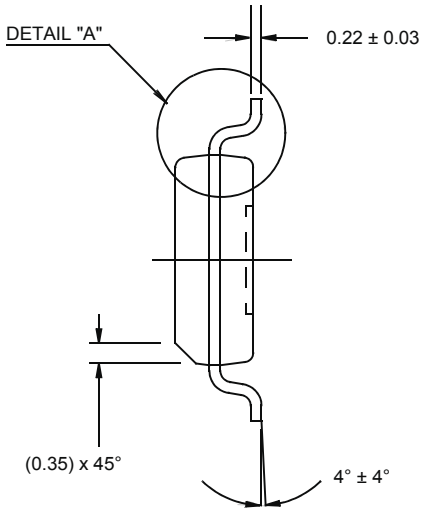
M8.15E

8 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

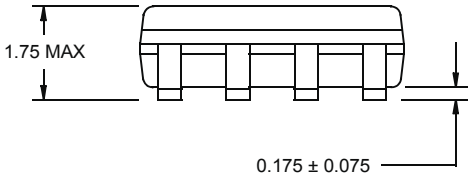
Rev 0, 08/09



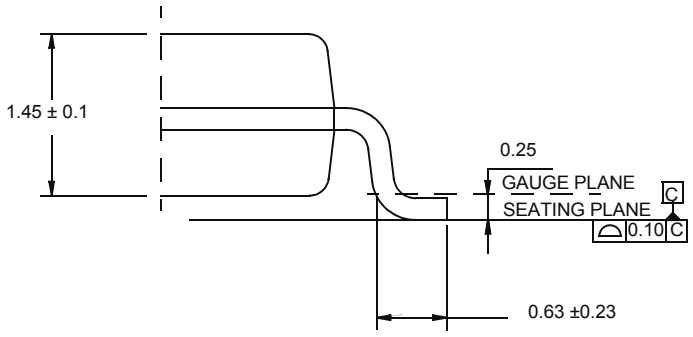
TOP VIEW



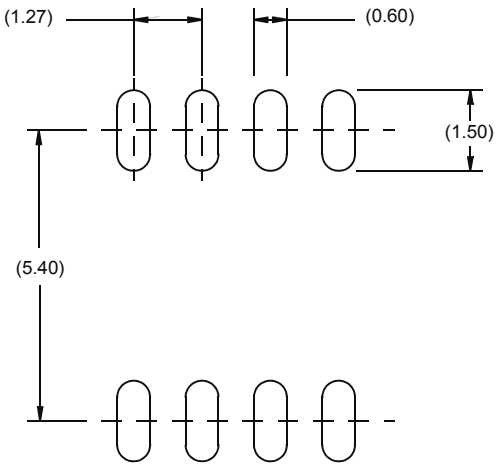
SIDE VIEW “B”



SIDE VIEW “A”



DETAIL "A"



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

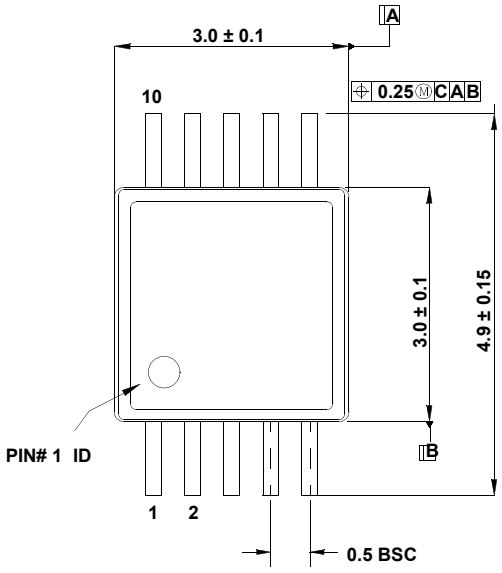
1. Dimensions are in millimeters.
   Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension does not include interlead flash or protrusions.
   Interlead flash or protrusions shall not exceed 0.25mm per side.
5. The pin #1 identifier may be either a mold or mark feature.
6. Reference to JEDEC MS-012.

Package Outline Drawing

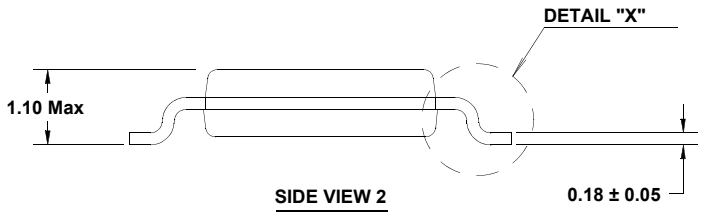
M10.118A (JEDEC MO-187-BA)

10 LEAD MINI SMALL OUTLINE PLASTIC PACKAGE (MSOP)

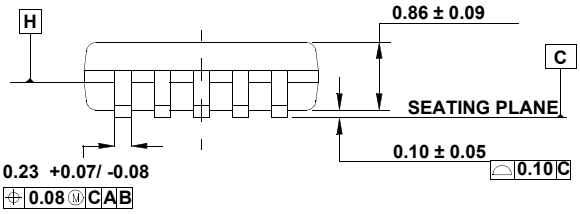
Rev 0, 9/09



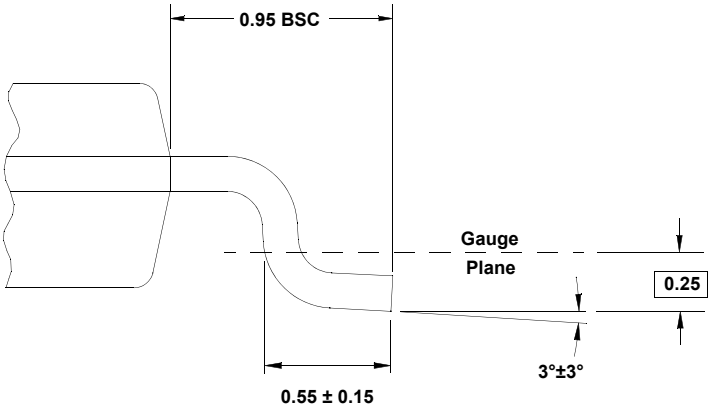
TOP VIEW



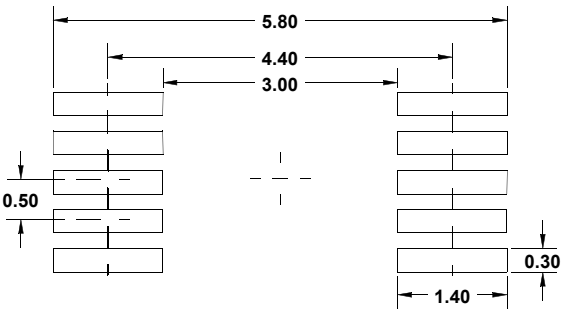
SIDE VIEW 2



SIDE VIEW 1



DETAIL "X"



TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
2. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
3. Plastic or metal protrusions of 0.15mm max per side are not included.
4. Plastic interlead protrusions of 0.25mm max per side are not included.
5. Dimensions “D” and “E1” are measured at Datum Plane “H”.
6. This replaces existing drawing # MDP0043 MSOP10L.